



Agency Recognitions

Agency	Agency File Number
27.	E128662

Maximum Ratings and Thermal Characteristics (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Junction Temperature	T_{J}	-55 to 125	°C
Storage Temperature	T _{STG}	-55 to 150	°C
Current Rating ¹	I _{PP}	3	kA
Typical Thermal Resistance Junction to Lead	R _{eJL}	10	°C/W
Typical Thermal Resistance Junction to Ambient	R _{eJA}	50	°C/W

Note:

1. Rated min $\rm I_{\rm pp}$ measured with 8/20µs pulse.

Functional Diagram



Description

The LTKAK3 series offers superior clamping characteristics over standard S.A.D. technologies by virtue of the Littelfuse Foldbak technology, which provides a clamping voltage lower than the avalanche voltage (but above the rated working voltage). Therefore, any voltage rise due to increased current conduction is contained to a minimum, providing the best possible protection level. This LTKAK3 series can be combined in series or parallel solutions to offer various clamping levels and surge withstand options.

The LTKAK3 SMT package provides a more compact PCB layout than typical through-hole TO-218 AK TVS components.

Features & Benefits

- Compact design having the Hi Power TVS in surface mount package
- Patent granted package design
- Foldback Technology for superior clamping factor
- Tube or tape and reel pack options available
- Ideal for automatic pick and place assembly and reflow process to reduce the manufacturing cost and increase the soldering quality as compared to axial leaded packages
- Meet MSL level1, per J-STD-020, LF maximun peak of 245 °C
- Halogen free and RoHS compliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)
- UL Recognized compound meeting flammability rating V-0
- UL Recognized as an Isolated Loop Circuit Protector to UL 497B

Surge Ratings

	Max.	Peak Pulse Curren	t (I _{PP})
Part Numbers	(8/20µs) (A)	(10/350µs) (A)	(10/1000µs) (A)
	min	min	min
LTKAK3-066C	3.000	800	500

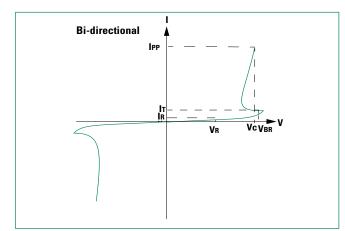
Electrical Characteristics (T_A=25°C unless otherwise noted)

Part Numbers	Standoff Voltage (V _R) Volts	Max. Reverse Leakage (Ι _Β) @V _Β μΑ	Reverse Breakdown V oltage (V _{BR}) @ I _T		Test Current I _T	Max. Clamping Voltage V _c @ I _{pp}	Max. Temp Coefficient OF V _{BR}	Max. Capacitance 0V bias 10kHz
		(I _R / ⊗ V _R μΛ	Min Volts	Max Volts	uA	V _c Volts	(%/°C)	(nF)
LTKAK3-066C	66	10	75	83	40	120	0.1	6

Note: Using 8/20µs wave shaped defined in IEC 61000-4-5.



I-V Curve Characteristics



 $\mathbf{P}_{\mathbf{PPM}}$ Peak Pulse Power Dissipation --

Max power dissipation

V_R Stand-off Voltage --Maximum voltage that can be applied to the TVS without operation

V_{BR} Breakdown Voltage --Maximum voltage that flows though the TVS at a specified test current (I₇)

V_c Clamping Voltage --

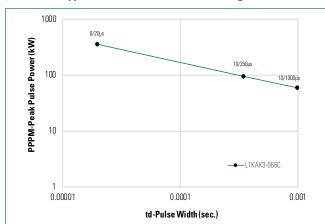
Peak voltage measured across the TVS at a specified lppm (peak impulse current)

Reverse Leakage Current --

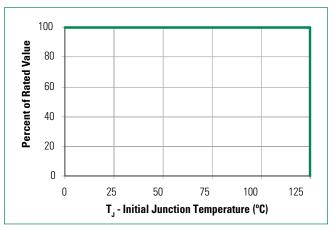
Current measured at V_n

Ratings and Characteristic Curves (T_A=25°C unless otherwise noted)

Typical Peak Pulse Power Rating Curve

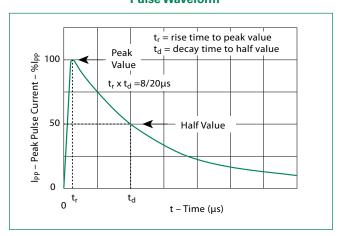


Peak Power Derating



Please contact Littelfuse for reliability or FIT/MTBF data, the performance is subject to vary and depends on

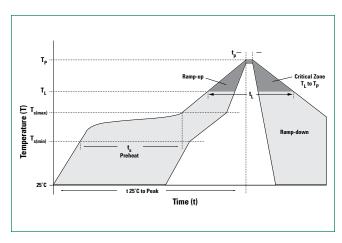
Pulse Waveform



LTKAK3 Series SMT0-218 - 3 kA

Soldering Parameters

Reflow Cond	Lead-free assembly		
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 - 180 secs	
Average ram	Average ramp up rate (Liquidus Temp (T _A) to peak		
T _{S(max)} to T _A -	T _{S(max)} to T _A - Ramp-up Rate		
Reflow	- Temperature (T _A) (Liquidus)	217°C	
nellow	-Time (min to max) (t _s)	60 - 150 seconds	
Peak Temper	245 ^{+0/-5} °C		
Time within	Time within 5°C of actual peak Temperature (t _p)		
Ramp-down	6°C/second max		
Time 25°C to	8 minutes Max.		
Do not exce	245°C		



Physical Specifications

Weight	0.149 ounce, 4.215 gram
Case	Compound encapsulated
Terminal	Tin plated lead, solderable per MIL-STD-202 Method 208

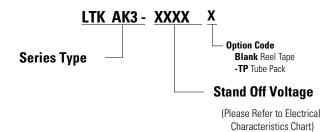
Flow/Wave Soldering (Solder Dipping)

Peak Temperature :	260°C
Dipping Time :	10 seconds
Soldering :	1 time

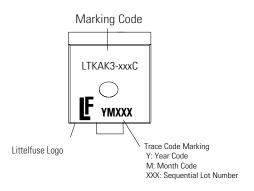
Environmental Specifications

High Temp Voltage Blocking (HTRB)	100 % DC reverse voltage rated 125 °C, 1008 hours JEDEC, JESD22-A-108
Biased Temp & Humidity (H3TRB)	80 % breakdown voltage (+85 °C) 85 %RH, 1008 hours JEDEC, JESD22-A-101
Unbiased Highly Accelerated Stress Test (UHAST)	96 hours at TA = 130 °C/85 %RH. JEDEC, JESD22-A-118
Temp Cycling (TC)	-55 °C to +125 °C, 15 min. dwell, 1000 cycles. JEDEC, JESD22-A104
Moisture Sensitivity Level (MSL)	85 %RH, +85 °C, 168 hours, 3 reflow cycles (+245 °C Peak). JEDEC, JEDEC-J-STD-020, Level 1
Resistance to Solder Heat (RSH)	+245 °C, 30 seconds JEDEC, JEDEC JESD22-A-111

Part Numbering System

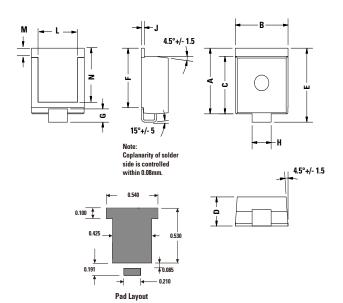


Part Marking System





Dimensions - SMTO-218

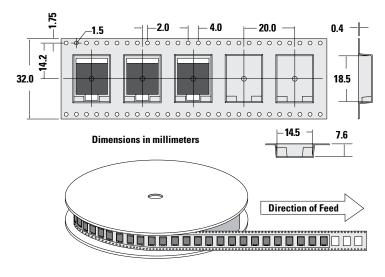


Dimension	Inches		Millimeters	
Dimension	Min	Max	Min	Max
Α	0.621	0.655	15.78	16.63
В	0.529	0.594	13.43	15.09
С	0.544	0.561	13.83	14.24
D	0.273	0.285	6.94	7.24
E	0.702	0.737	17.82	18.72
F	0.567	0.587	14.40	14.90
G	0.087	0.126	2.20	3.20
Н	0.193	0.222	4.89	5.65
J	0.028	0.033	0.72	0.85
L	0.400	0.440	10.17	11.17
M	0.073	0.112	1.85	2.85
N	0.510	0.533	12.95	13.55

Packaging

Part Number	Weight	Packing Mode	Base Quantity
LTKAK3-xxxC	4.215g	Tape & Reel – 32mm/13" tape	400
LTKAK3-xxxC-TP	4.215g	Tube Pack	100(25/Tube)

Tape and Reel Specification



Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littlefuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at http://www.littlefuse.com/disclaimer-electronics.

